

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 5, 6, 8 and 15-17 without prejudice and amend claims 7 and 10-14 as follows:

**LISTING OF CLAIMS:**

Claim 1 (Withdrawn) A holding jig comprising:  
an elastic material wherein at least the surface thereof is adhesive and conductive,  
and wherein an electronic part or component constituting the electronic part is holdable by  
the adhesive strength of the surface of the elastic material.

Claim 2 (Withdrawn) The holding jig according to claim 1, wherein the elastic  
material is made to be conductive by adding conductive material to the elastic material.

Claim 3 (Withdrawn) The holding jig according to claim 1, wherein the elastic  
material is made to be conductive by installing a wiring using conductive material on the  
surface of the elastic material.

Claim 4 (Withdrawn) The holding jig according to claim 1, wherein the elastic  
material is made to be conductive by installing a wiring using conductive material inside  
the elastic material, the wiring being exposed on the surface of the elastic material.

Claim 5 (Canceled)

Claim 6 (Canceled)

Claim 7 (Currently Amended) A method of manufacturing electronic parts, comprising:

holding a substrate on a surface of a holding jig made of an elastic material, in which at least the surface of said elastic material is adhesive, by the adhesive strength of said surface; and

mounting and electrically connecting an element on said substrate while the substrate is held on the surface of the elastic material; and

applying ultrasonic waves to the bonding portion at which the electric connection is performed.

Claim 8 (Canceled)

Claim 9 (Original) The method of manufacturing electronic parts according to claim 7, wherein the hardness of the elastic material is a rubber hardness degree of at least A30.

Claim 10 (Currently Amended) The method of manufacturing electronic parts according to claim 7 9, wherein the step of holding said substrate includes using a the

holding jig which comprises heat-resistant material having a heat-resistance temperature of about 250°C.

Claim 11 (Currently Amended) The method of manufacturing electronic parts according to claim 7 9, wherein the step of holding said substrate includes using ~~a~~ the holding jig which includes a laminate structure of a hard plate and the elastic material.

Claim 12 (Currently Amended) The method of manufacturing electronic parts according to claim 7 9, wherein the elastic material comprises silicone resin.

Claim 13 (Currently Amended) The method of manufacturing electronic parts according to claim 7 9, wherein the mounting process includes a wire bonding process.

Claim 14 (Original) The method of manufacturing electronic parts according to claim 7 9, wherein the mounting process includes a bump bonding process.

Claim 15 (Canceled)

Claim 16 (Canceled)

Claim 17 (Canceled)